

CLAIMS

Claims 1-67 (canceled)

68. (canceled): A chip package comprising:

packaging material having a first side, an opposed second side, a third side disposed between the first side and the second side, and an opposed fourth side disposed between the first side and the second side; and

a lead extending from the first side of the packaging material,
a separate clip having a left connector portion, a right connector portion,
and a bridge portion;

wherein in assembly

the left connector portion generally extends along the second side,
the right connector portion generally extends along the third side, and
the bridge portion generally extends along the fourth side, and
when the right connector portion and the left connector portion each
mate with a base, the clip helps retain the packaging material in contact with the
base by exerting a force on the fourth side.

69. (canceled): The chip package of claim 68, the packaging material having a third side, and further comprising a second clip portion extending from the third side of the packaging material.

1 70. (previously amended): The chip package of claim 74, further comprising a
2 flexible insert residing between the lead and the first side of the packaging
3 material, wherein the flexible insert supplies spring force when the lead is
4 compressed.

5
6 71. (previously amended): The chip package of claim 70, wherein the flexible
7 insert is cylindrical.

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9 72. (previously added): The chip package of claim 71, wherein the flexible
10 insert is a compliant material.

11
12 73. (previously added): The chip package of claim 72, wherein the compliant
13 material is an elastomer.

14
15 74. (currently amended): The chip package of claim ~~6891~~, wherein the lead is
16 substantially C-shaped.

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18 75. (previously added): The chip package of claim 74, wherein the lead is
19 compressible.

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21 76. (canceled): The chip package of claim 70, wherein the lead is compressible.

22
23 77. (currently amended): The chip package of claim ~~6891~~, further comprising a
24 pin extending from the packaging material to guide the chip package in the base.

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1 78. (canceled): The chip package of claim 69, wherein the first and second clip
2 portions are integral with the packaging material.

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4 79. (canceled): The chip package of claim 68, wherein the lead is a flexible
5 metallic material.

6
7 80. (currently amended): The chip package of claim ~~79~~91, wherein the lead
8 ~~metallic material~~ comprises beryllium-copper.

9
10 81. (currently amended): The chip package of claim ~~68~~91, wherein the
11 packaging material is comprised of a flexible material.

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13 82. (previously added): The chip package of claim 81, wherein the flexible
14 material supplies spring force when the lead is compressed.

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16 83. (currently amended): The chip package of claim ~~68~~91, wherein the
17 packaging material comprises silicone rubber.

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19 84. (canceled): The chip package of claim 68, further comprising a cam
20 follower extending from the packaging material.

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22 85. (currently amended): The chip package of claim ~~68~~91, further comprising
23 an integrated circuit disposed in the packaging material.

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25

86. (currently amended): The chip package of claim ~~68~~91, wherein the chip is flexible.

87. (canceled): The chip package of claim 68, wherein the packaging material has a bottom-facing housing that extends laterally from the packaging material, the bottom-facing housing having a pocket formed therein.

88. (canceled): The chip package of claim 87, wherein an end of the lead is disposed within the pocket when the lead is compressed.

89. (withdrawn): A package, comprising:
an integrated circuit enclosed with the package,
substantially C-shaped leads at a first end of the package,
a guide member on a side of the package, wherein the guide member has a ramp, and
mechanical support pins at a second end of the package opposite the first end,
wherein the package resides substantially horizontally with respect to a circuit board when the package is inserted in a base assembly coupled to the circuit board.

90. (withdrawn): The package of claim 89, wherein the integrated circuit is a dynamic random access memory device.

1 91. (new): A chip package comprising:

2 packaging material having a first side;

3 a flexible lead extending from the first side; and

4 a clip extending from the packaging material.

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6 92. (new): The chip package of claim 70, wherein the lead is compressible.

7
8 93. (new): The chip package of claim 74 furthermore comprising an

9 indentation; and wherein the lead extends into the indentation.

10
11 94. (new): The chip package of claim 74 furthermore comprising an

12 indentation; and wherein the lead extends into the indentation when the lead is

13 compressed.

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15 95. (new): The chip package of claim 91, wherein the clip is integral with the

16 packaging material.

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18 96. (new): The chip package of claim 91, wherein the chip package is an

19 assembly that comprises the clip and the packaging material, the clip and the

20 packaging material each being separate from the other.

21
22 97. (new): A system comprising the chip package of claim 68 and a base unit,

23 the base unit comprising a slotted guide; and the chip package further comprising a

24 pin configured to be received by the slotted guide.